

12-18-01

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THE COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

Docket No. **TS01-1372**

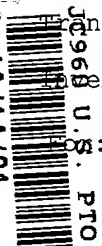
Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **HARRY CHUANG**

Title: **LOCALIZED SLOTS FOR STRESS RELIEVE IN COPPER**

12/14/01



Enclosed are:

- ☒ 2 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Taiwan Semiconductor Manufacturing Company**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- ☒ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 740.
TOTAL CLAIMS	46 -20=	26	x 18 =	\$ 468.
INDEP CLAIMS	2 -3=	0	x 84 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
SUB TOTAL				\$ 1,208.
ASSIGNMENT				\$40.
TOTAL				\$ 1,248.

☒ Please charge my Deposit Account No. 19-0033 in the amount of **\$ 1,248.** A duplicate